Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSIII)

2SK3017

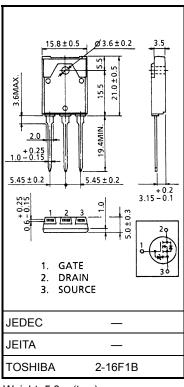
DC-DC Converter, Relay Drive and Motor Drive Applications

• Low drain-source ON resistance : $RDS (ON) = 1.05 \Omega (typ.)$ • High forward transfer admittance : $|Y_{fs}| = 7.0 S (typ.)$ • Low leakage current : $IDSS = 100 \mu A (max) (VDS = 720 V)$

• Enhancement mode $: V_{th} = 2.0 \sim 4.0 \text{ V (Vps} = 10 \text{ V, Ip} = 1 \text{ mA})$

Absolute Maximum Ratings (Ta = 25°C)

Characteris	stics	Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	900	V
Drain-gate voltage (R	_{SS} = 20 kΩ)	V_{DGR}	900	V
Gate-source voltage		V_{GSS}	±30	V
Drain current	DC (Note 1)	I_{D}	8.5	Α
	Pulse (Note 1)	I_{DP}	25.5	Α
Drain power dissipation	n (Tc = 25°C)	PD	90	W
Single pulse avalanche energy (Note 2)		E _{AS}	966	mJ
Avalanche current		I _{AR}	8.5	Α
Repetitive avalanche e	nergy (Note 3)	E _{AR}	9	mJ
Channel temperature		T _{ch}	150	°C
Storage temperature ra	ange	T _{stg}	-55~150	°C



Weight: 5.8 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	1.39	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	41.6	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 24.5 mH, R_{G} = 25 Ω , I_{AR} = 8.5 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device.

Please handle with caution.

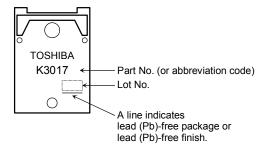
Electrical Characteristics (Ta = 25°C)

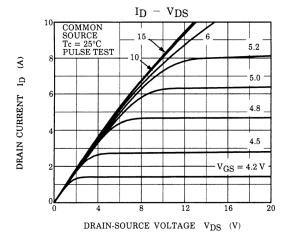
Charac	eteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I _{GSS}	V _{GS} = ±30 V, V _{DS} = 0 V	_	_	±10	μΑ
Gate-source bre	eakdown voltage	V (BR) GSS	I _G = ±10 μA, V _{DS} = 0 V	±30	_	_	V
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 720 V, V _{GS} = 0 V	_	_	100	μA
Drain-source br	eakdown voltage	V _{(BR) DSS}	I _D = 10 mA, V _{GS} = 0 V	900	_	_	V
Gate threshold v	oltage/	V_{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source O	N resistance	R _{DS (ON)}	V _{GS} = 10 V, I _D = 4 A	_	1.05	1.25	Ω
Forward transfer	r admittance	Y _{fs}	V _{DS} = 15 V, I _D = 4 A	3.5	7.0	_	S
Input capacitano	e	C _{iss}			2150	_	
Reverse transfe	r capacitance	C _{rss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz		35	_	pF
Output capacitance		C _{oss}			220	_	
Switching time	Rise time	t _r	$V_{GS} \stackrel{10 \text{ V}}{\circ} V \stackrel{\text{I}_{D} = 4 \text{ A}}{\circ} V_{OUT}$ $R_{L} = 100 \Omega$ $V_{DD} = 400 \text{ V}$	_	25	_	- ns
	Turn-on time	t _{on}		_	60	_	
	Fall time	t _f		_	25	_	
	Turn-off time	t _{off}	Duty $\leq 1\%$, $t_{\rm W} = 10 \mu \rm s$	_	120	_	
Total gate charge (Gate-source plus gate-drain)		Qg		ı	70	_	
Gate-source charge		Q_{gs}	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 8 \text{ A}$		37	_	nC
Gate-drain ("miller") charge		Q _{gd}			33	_	

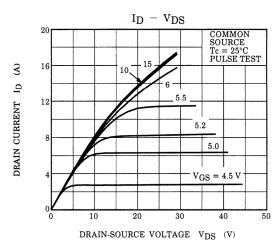
Source-Drain Ratings and Characteristics (Ta = 25°C)

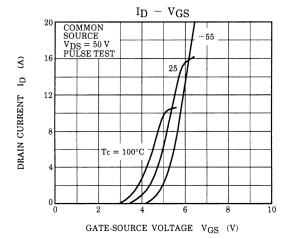
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	-	8.5	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	25.5	Α
Forward voltage (diode)	V_{DSF}	I _{DR} = 8.5 A, V _{GS} = 0 V	_	_	-1.9	V
Reverse recovery time	t _{rr}	I _{DR} = 8.5 A, V _{GS} = 0 V		1300		ns
Reverse recovery charge	Qrr	dl _{DR} / dt = 100 A / μs		14.5	-	μC

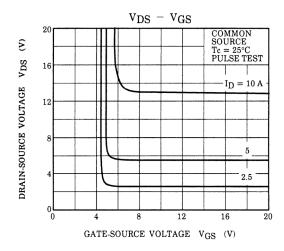
Marking

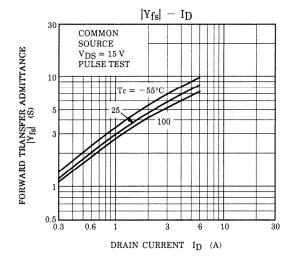


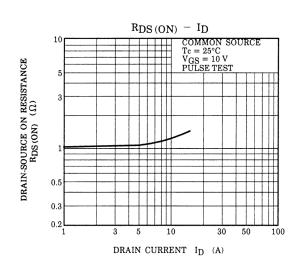


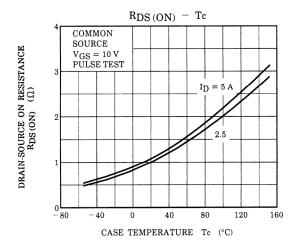


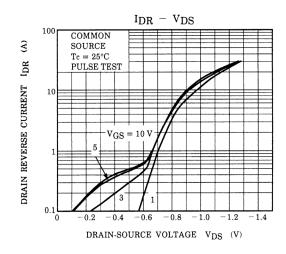


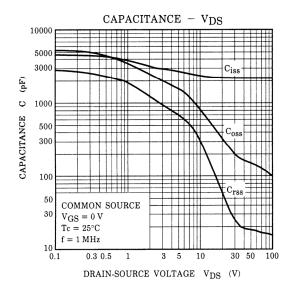


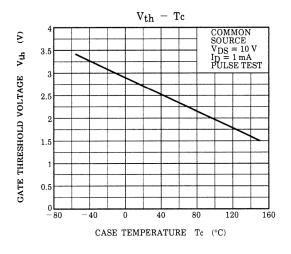


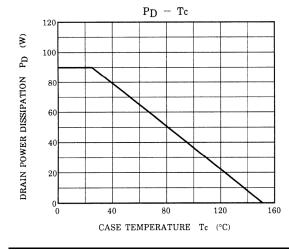


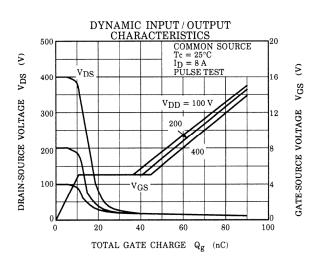




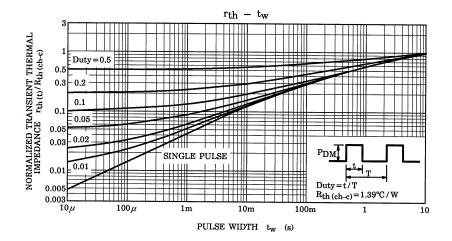


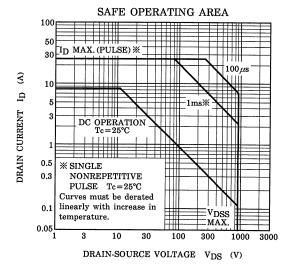


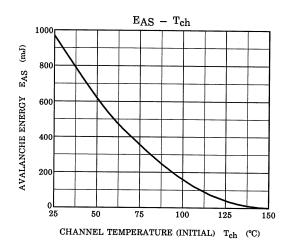


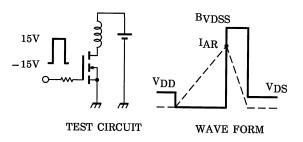


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$$\begin{split} RG &= 25~\Omega \\ V_{DD} &= 90~V,~L = 24.5~mH \end{split}$$

$$E_{AS} = \frac{1}{2} \cdot L \cdot I^{2} \cdot \left(\frac{BVDSS}{BVDSS - VDD} \right)$$

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